IN THE CLAIMS

1. (currently amended) A component for making connections in a microelectronic assembly comprising:

(a) a dielectric layer having first and second surfaces;

(b) a plurality of elongated conductors on said first surface; and

(c) slots in said dielectric layer extending through the dielectric layer under ~~beneath~~ said conductors from said first surface to said second surface, said slots extending in the direction of elongation of said conductors.

2. (original) A component as claimed in claim 1 further comprising a dispersible conductive material disposed in said slots.

3. (previously presented) A component as claimed in claim 1 wherein at least one of the slots is empty.

4. (previously presented) A component as claimed in claim 1 wherein at least one of the slots is devoid of conductive material.

5. (previously presented) A component as claimed in claim 1 wherein the dielectric layer is solid dielectric.

6. (canceled)